

## **IN THE SPECIFICATION**

Please amend the specification as follows:

Replace the paragraph beginning at page 2, line 18, with the following replacement paragraph:

---According to the present invention there is provided an optical transceiver module comprising a housing having disposed therein a transmitter and a receiver, characterized in that ~~said the~~ housing further comprises a pair of ~~rails~~ grooves disposed on opposite sides of said housing, ~~said rail~~ the grooves having a plurality of spring-like fingers arranged to enable ~~said the~~ module to be removably inserted into a suitably configured board.---

Replace the paragraph beginning at page 4, line 12, with the following replacement paragraph:

---In figure 2, the fibre optic transceiver module 1 according to the present invention is shown comprising housing 2, bezel 3, apertures 4 and 5, rail means 6, and module PCB connector means 7. The housing and bezel are preferably made of metal. However, other suitable material, such as a suitably loaded polymer could be used. The housing is configured with a series of fins 9, which are arranged in rows and act as heat sinks. The apertures provide access to the internal components of the module. Aperture 4 provides access to an optical signal receiver 52(not shown) and aperture 5 provides access to an optical signal transmitter 53(not shown). Alternatively, aperture 4 can provide access to the receiver and aperture 5 can provide access to the transmitter.---

Replace the paragraph beginning at page 5, line 1, with the following replacement paragraph:

---~~Rail~~ Groove means 6 are disposed on the sides of the housing in a manner so that the module can be inserted into a motherboard, with the rail means acting as a guide. The ~~rail~~ groove means may further act to support the module once inserted into the chassis. As will be apparent, a further groove ~~rail~~ means (not visible in figure 2) is disposed on the opposite side of the housing.---

Replace the paragraph beginning at page 5, line 16, with the following replacement paragraph:

---As can be seen in figure 4, module 1 consists of an upper half 110 and a lower half 112. During assembly the upper and lower halves are sandwiched together and held together by suitable connection means such as screws 118 that are shown in figure 3. An electrically conductive gasket 115, known in the art as an EMI gasket, is disposed between the upper and lower halves. The EMI gasket functions to ensure good electrical connection between the two halves. In the embodiment shown here the module is approximately 4 inches long, 1.5 inches wide, and 1 inch tall. However, as will be appreciated, the module could have other dimensions without departing from the scope of the present invention.---

Replace the paragraph beginning at page 7, line 27, with the following replacement paragraph:

---As previously mentioned, and now shown in more detail in figures 7, 8 and 9, where parts also appearing in figures 2-6 bear identical numerical designation, ~~rail~~ groove means 6 comprises a plurality of spring like fingers 260 flexibly attached to an interposer 262. The spring fingers and interposer are preferably made of metal and form a single piece part. As will be appreciated, a substantially identical groove ~~rail~~ means is disposed on the opposite side of the module.---

Replace the paragraph beginning at page 8, line 6, with the following replacement paragraph:

---The ~~rail-groove~~ means are inserted into motherboard 35 via a ~~groove-rail~~ 270 formed in the ~~housing~~motherboard. The spring fingers are arranged so as to accept a range of motherboard thickness, while still securely holding the module in place. For example, the spring fingers are arranged to accept motherboards with thickness ranging from 2mm to 3.1mm.---